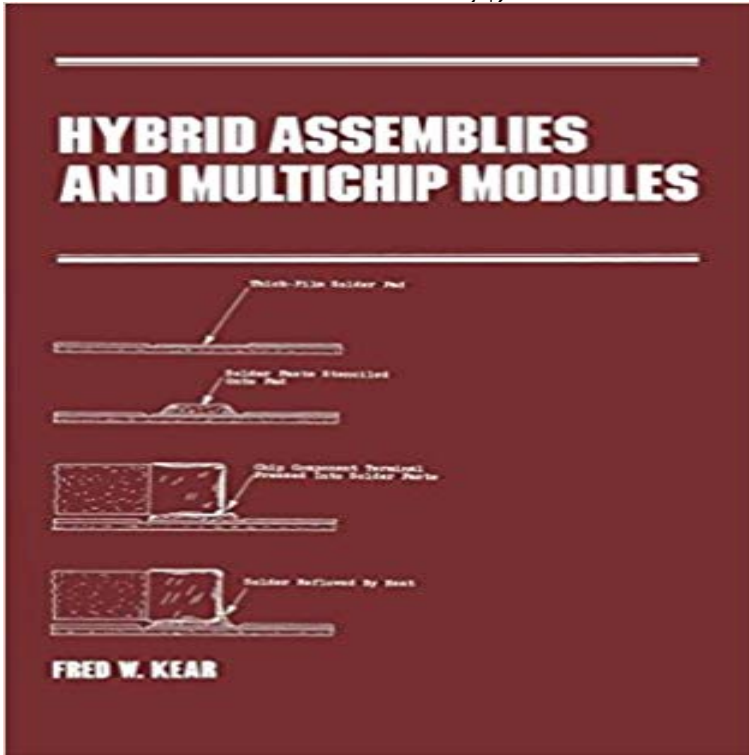


Hybrid Assemblies and Multichip Modules (Manufacturing Engineering and Materials Processing)



Providing a description of design considerations from the users viewpoint, this detailed reference discusses the materials used in manufacturing hybrid assemblies and multichip modules - illustrating how these products are created for a wide range of applications. Examining the current state of hybrid assembly technology, Hybrid Assemblies and Multichip Modules: provides a thorough overview of substrate materials and metals used for conductors, addressing multilayer materials and overglazes; explicates design considerations such as circuit layout, component placement, thermal management and interface problems; clarifies the manufacturing techniques used for multi-layer thick-film circuits and multilayer substrates; and explains soldering and other attachment methods for discrete components. Focusing primarily on electronic assemblies that use ceramic substrates, Hybrid Assemblies and Multichip Modules should serve as a comprehensive resource for manufacturing, electrical and electronics, and automotive engineers; manufacturing managers; hybrid assembly designers; hybrid assembly users; printed circuit designers, fabricators and users; and graduate-level students in manufacturing engineering and electronic packaging courses.

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